About HDP User Group

HDP User Group is a non profit organization based in Scottsdale, AZ, USA, that offers memberships to companies involved in the supply chain of specifying or producing products using high density electronic packages (**High Density Packaging**). HDP is an international industry led group that organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance.

Our Mission is to reduce the costs and risks for the Telecommunications and Computer industries when utilizing electronic packaging. This is done by improving cooperation between system integrators, contract assembly manufacturers, and suppliers in the high density packaging development and design process, using member resources supplemented by a small staff.

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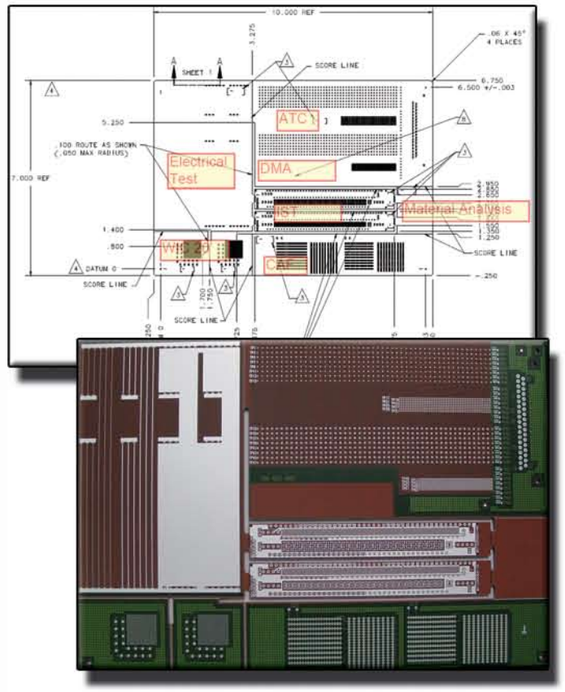
Project Focus Areas

HDP User Group promotes activity in a diverse range of technical projects ranging from extensive reliability testing programs through guideline generation initiatives. Projects are initiated by the members to address both technical challenges and opportunities. Projects are currently underway in the following focus areas:

* Halogen-Free
* Lead Free
* Opto-Electronics
* Power Supplies
* Semiconductor Packaging
* Printed Wiring Board Technologies
* Packaging and Assembly Reliability
* Emerging Technologies

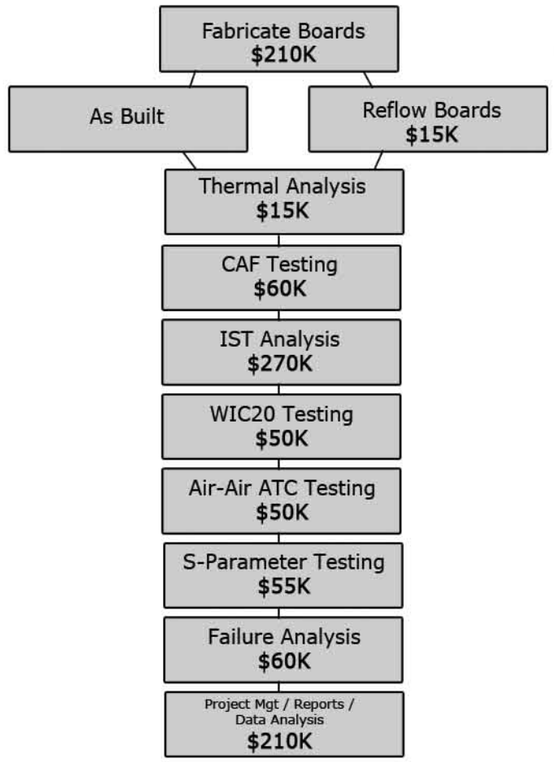


The Power of Collaboration

HDP User Group operates on the concept that by bringing companies together to cooperate and share key resources and knowledge the cost to each project participant to undertake vital research work is a fraction of the cost of going it alone.

Project: Evaluate latest generation of PWB laminates to asses mechanical and electrical performance consistency before and after multiple Pb-fre solder reflow process stages. 20 different materials evaluated - 27 different board constructions.

Test Program: Figures indicate cost of services on commercial market.



All services contributed by project members. Total cost to conduct same project as an in-house program using commercial services is $980K.

Are You Competitive?

HDP USER GROUP INTERNATIONAL, INC.®

Technology Development in Today's Global Environment

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